客户图

NOTES:

1.MATERIAL:

1.1 HOUSING: LCP WHITE,UL94 V-0

1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AERA,80u" MIN MATTE TIN PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

2.1 CURRENT RATING: 3.0 AMP,AC/DC

2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V,AC/Minute

2.3 CONTACT RESISTANCE: 20mΩ MAX.

2.4 INSULATION RESISTANCE: 1000 mΩ Min

2.5 Operation Temperature:-55°C to125°C

3.SALT SPRAY TEST:

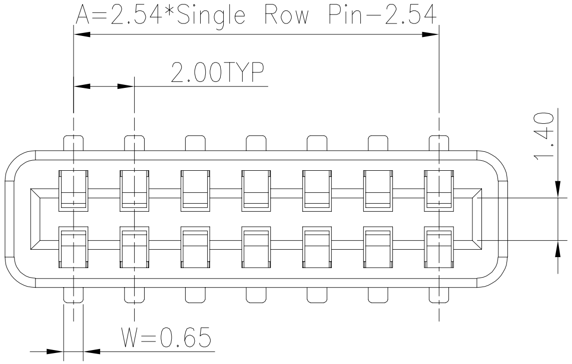
3.1 CONCENTRATION IS 5%, THE TEMPERATUREIS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

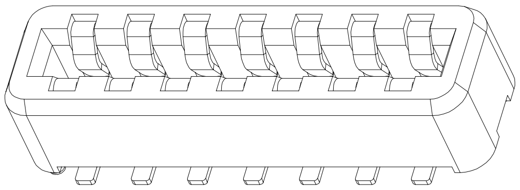
4.Max Processing Temp:265°C Seconds 10S

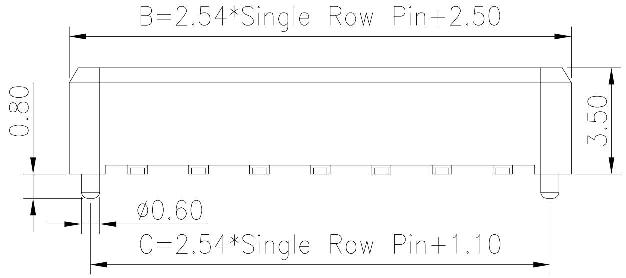
5.ORDER INFORMATION:

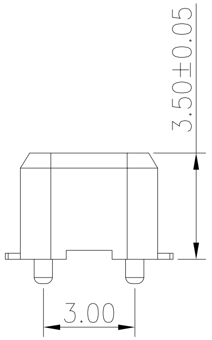
61G3-F XXX S1 035 R 01

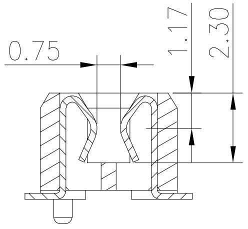
Pin数码	端子电镀：	高度：	包装方式：
SEE TABLE	S1=1u"Gold/Tin	035=3.50mm	R=REEL
004=2*2PIN	S2=3u"Gold/Tin		
...	S3=5u"Gold/Tin		
050=2*25PIN	S4=10u"Gold/Tin		

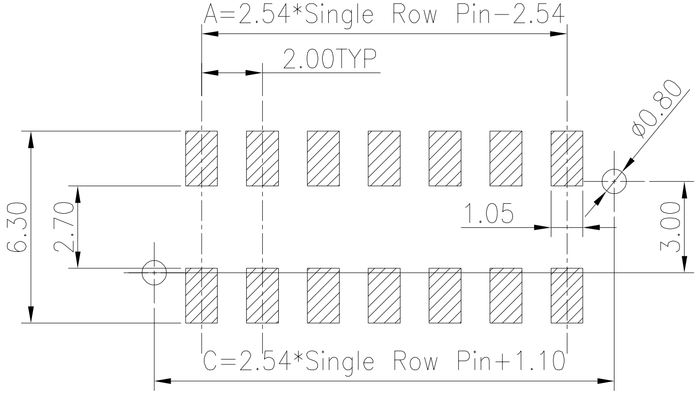












RECOMMENDED PCB LAYOUT(TOP SIDE)

PCB BOARD TOLFRANCF±0.05

A0		NEW	———	———
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE

OPERATION				
X.X	±0.40	DRAW	Mr.Zeng	2025.12.03
X.XX	±0.25	DESIGN	Jensen	2025.12.03
X.XXX	±0.15	CHECK	Jack	2025.12.03
Angle	±3°	APPROVE	Andy	2025.12.03
DIM.	TOL	UNIT	mm	SCALE 1:1

SOLEPiN PROFESSIONAL CONNECTOR

东莞市硕品电子有限公司

DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE	A4	PART NO.	61G3-F XXX S1 035 R 01
SHEET	1/1	TITLE:	61G3 2.00mm 金手指 SMT 连接器
PROJ.	⌖	DRAW NO.	SP-1811